

SPECIFICATION

Paragraph starting on Page 8, line 9, and ending on line 16 was amended as follows:

With the disclosed interposer, an IC is not directly mechanically and electrically attached to the antenna. The IC is attached to an interposer so that it can be positioned at the connection ends of the antenna circuit. The interposer comprises a base substrate film with two printed pads. An IC is connected between the two electrically isolated pads. The interposer can provide added structural support and can secure the internal components. Other flush mount components, such as light emitted diodes (LEDs), can be attached using similar techniques. This removes the limitations for precise placement on the leads of a circuit. Additionally, IC's can be mounted on conventional circuits via an interposer.

Paragraph starting on Page 15, line 4 and ending on line 16 was amended as follows:

The pressure sensitive adhesive does not require the application of heat to adhere the components. The pressure sensitive adhesive can be cured through radiation (ultraviolet (UV) or electron beam (EB)) or can be conventionally dried (either as solvent-based or water-based). UV cured adhesives have been used as the preferred curing/drying method, and for high-speed production, a quick curing solution is required. H.B. Fuller has a part for such a formula, namely Solar Cure RT-7575. Ideally, the anisotropically conductive adhesive is a printable, UV-quick curable, pressure sensitive adhesive that maintains its flexibility. Adhesives to be avoided include those that require UV, heat or microwave curing that have an unacceptable cure time for high speed production. The pressure sensitive adhesive film 38 ideally has a minimal resistance, but metal or other conductors adversely affect the adhesion. The pressure sensitive adhesive film 38 must be suitable for high speed applications, such as having properties as a high speed insertion. It should preferably maintain flexibility without losing its connection.

CLAIMS

Claim 1 was cancelled without prejudice or disclaimer.

2. (amended) The [interposer] RFID tag of claim [1] 28 wherein [the] a pattern of the [electrical] first and second contact pads is selected from a group comprising butterfly, propeller, polygon and [or] bow-tie patterns.

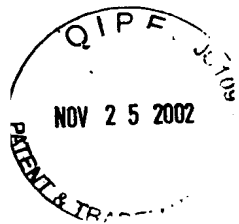
3. (amended) The [interposer] RFID of claim [1] 28 wherein [the] a conductive adhesive is [an anisotropically conductive pressure sensitive] applied to at least a portion of the first and second contact pads.

Claims 4 -12 were canceled without prejudice or disclaimer.

ABSTRACT

The abstract was amended as follows:

[An interposer and a method of manufacturing a flexible radio frequency (RF) type device having an IC and thin film circuits, such as an antenna. The device is made by using an easy-t-insert interposer subassembly with pre-position ICs to mechanically and electrically attach an IC to the thin film circuit. A method of mass producing radio frequency devices comprising antennas and ICs on interposers that are physically and electrically connected to the antenna using a pressure sensitive adhesive] A radio frequency identification tag comprising a first substrate and a second substrate is disclosed. An antenna element is disposed on the first substrate, and a first contact pad and a second contact pad is disposed on the second substrate. A circuit is coupled to the first and second contact pads, and the first and second contact pads are designed to make electrical contact with the antenna element.



As amended
Nov. 20, 2002
(marked up version)

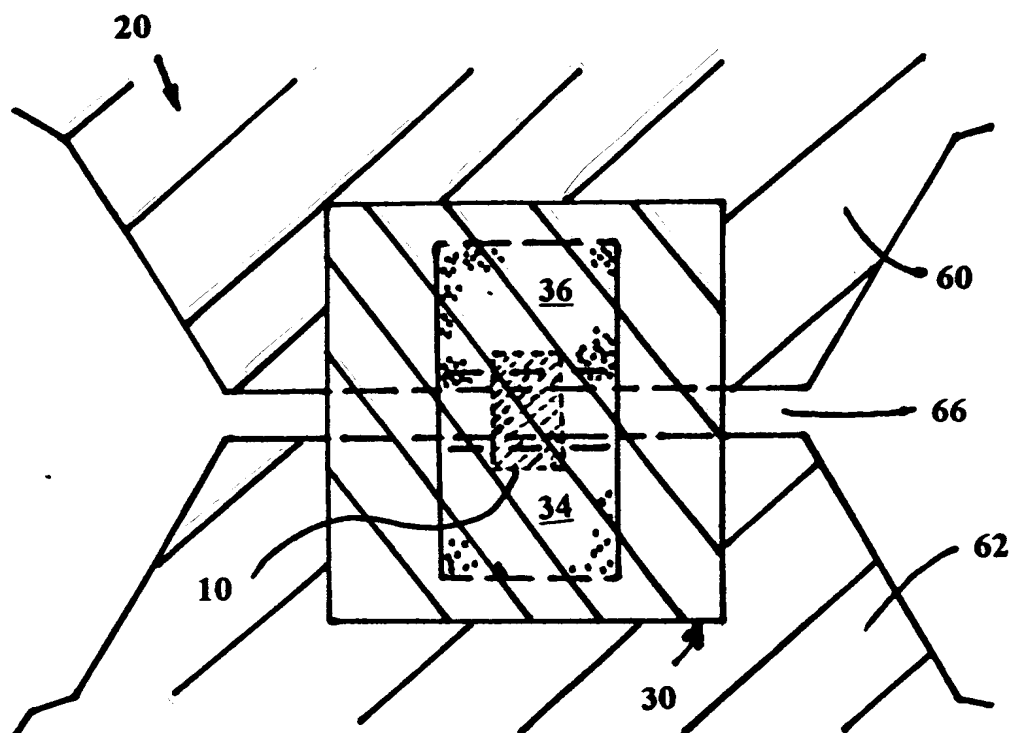


Fig. 2

As Amended
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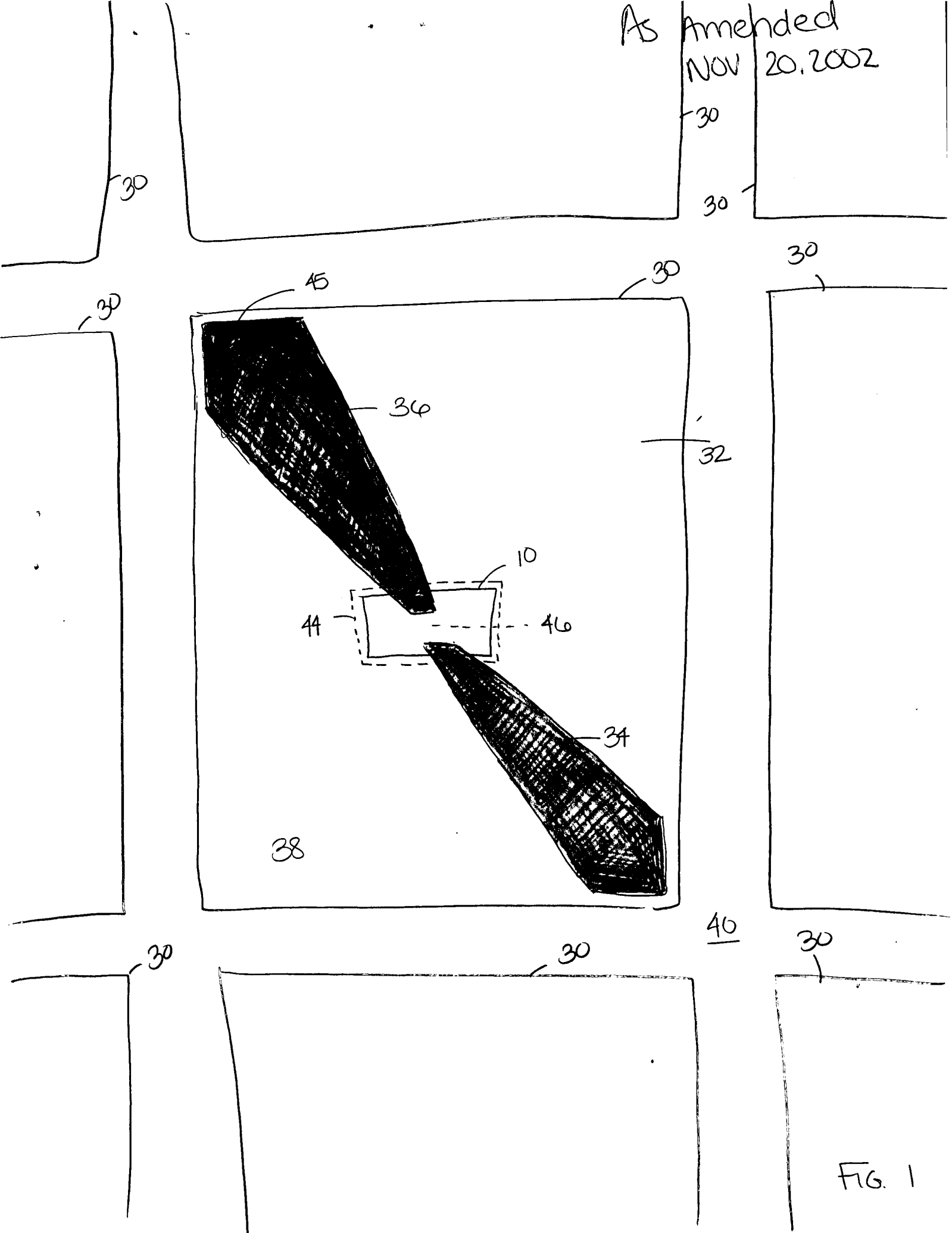


FIG. 1